

## N-CHANNEL ENHANCEMENT MOS FET

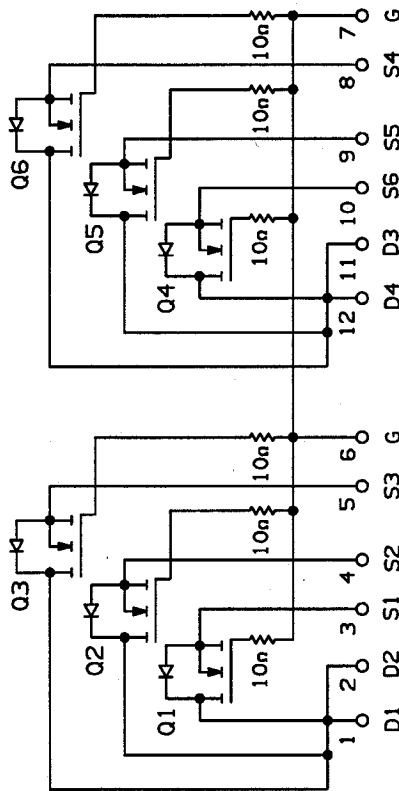
400V, 150A, 0.035Ω

SDF150NA40 HE

### FEATURES

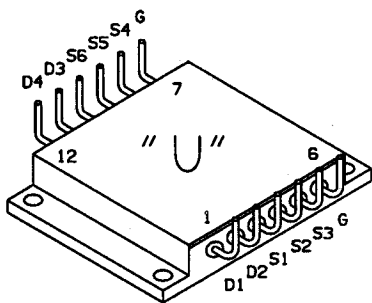
- RUGGED PACKAGE
- HI-REL CONSTRUCTION
- CERAMIC EYELETS
- LEAD BENDING OPTIONS
- COPPER CORED 52 ALLOY PINS
- LOW IR LOSSES
- LOW THERMAL RESISTANCE
- OPTIONAL MIL-STD-883 SCREENING

### SCHEMATIC



### STANDARD BEND CONFIGURATION

HE



(CUSTOM BEND OPTIONS AVAILABLE)

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL		UNITS
DRAIN-SOURCE VOLTAGE	V <sub>DSS</sub>	400	V <sub>dc</sub>
DRAIN-GATE VOLTAGE (R <sub>GS</sub> =1.0MΩ)	V <sub>DGR</sub>	400	V <sub>dc</sub>
GATE-SOURCE VOLTAGE CONTINUOUS	V <sub>GS</sub>	±20	V <sub>dc</sub>
DRAIN CURRENT CONTINUOUS (T <sub>c</sub> = 25°C)	I <sub>D</sub>	150	A <sub>dc</sub>
DRAIN CURRENT PULSED	I <sub>DM</sub>	600	A
TOTAL POWER DISSIPATION	P <sub>D</sub>	1250	W
POWER DISSIPATION DERATING > 25°C		10.0	W/°C
OPERATING & STORAGE TEMP.	T <sub>J</sub> /T <sub>stg</sub>	-55 TO +150	°C
THERMAL RESISTANCE	R <sub>thJc</sub>	0.10	°C/W
MAX. LEAD TEMPERATURE	TL	300	°C

### ELECTRICAL CHARACTERISTICS T<sub>c</sub> = 25°C (UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
DRAIN-SOURCE BREAKDOWN VOLTAGE (1 & 2)	V(BR) <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250 μA	400	-	-	V
GATE THRESHOLD VOLTAGE	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250 μA	2.0	-	4.0	V
GATE SOURCE LEAKAGE	I <sub>GSS</sub>	V <sub>GS</sub> =±20 V	-	-	100	nA
ZERO GATE VOLTAGE DRAIN CURRENT	I <sub>DSS</sub>	V <sub>DS</sub> =MAX.RATING V <sub>GS</sub> =0	-	-	250	μA
		V <sub>DS</sub> =0.8 MAX.RATING V <sub>GS</sub> =0 T <sub>J</sub> =125°C	-	-	1000	μA
STATIC DRAIN-SOURCE ON-STATE RESISTANCE (2)	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10 V I <sub>D</sub> =13A	-	-	0.20	Ω
FORWARD TRANS-CONDUCTANCE (2)	g <sub>fs</sub>	V <sub>DS</sub> ≥ 50 V I <sub>DS</sub> =13A	14	-	-	S(U)
INPUT CAPACITANCE	C <sub>ISS</sub>		-	4100	-	pF
OUTPUT CAPACITANCE	C <sub>OSS</sub>	V <sub>GS</sub> =0V V <sub>DS</sub> =25 V f=1.0 MHz (3)	-	480	-	pF
REVERSE TRANSFER CAPACITANCE	C <sub>RSS</sub>		-	84	-	pF
TURN-ON DELAY	t <sub>d(on)</sub>	V <sub>DD</sub> =200V R <sub>G</sub> =4.3 Ω I <sub>D</sub> =25A R <sub>D</sub> =7.5 Ω	-	-	33	ns
RISE TIME	t <sub>r</sub>	(MOSFET SWITCHING TIMES ARE ESSENTIALLY INDEPENDENT OF OPERATING TEMP. NOTE 3)	-	-	140	ns
TURN-OFF DELAY	t <sub>d(off)</sub>		-	-	120	ns
FALL TIME	t <sub>f</sub>		-	-	99	ns
TOTAL GATE CHARGE (GATE-SOURCE PLUS GATE-DRAIN)	Q <sub>g</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =25A V <sub>DS</sub> =0.8 MAX.RATING	-	-	190	nC
GATE SOURCE CHARGE	Q <sub>gs</sub>	(GATE CHARGE IS ESSENTIALLY INDEPENDENT OF THE OPERATING TEMPERATURE NOTE 3)	-	-	27	nC
GATE-DRAIN ("MILLER") CHARGE	Q <sub>gd</sub>		-	-	93	nC

### TOTAL MODULE RATINGS AND CHARACTERISTICS T<sub>c</sub> = 25°C (UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	MAX.	UNITS
PIN-CASE ISOLATION	PCI	V <sub>CASE</sub> -PINS ALL PINS SHORTED TO CASE	10	-	mΩ
STATIC DRAIN-SOURCE ON-STATE VOLTAGE	V <sub>DS(ON)</sub>	V <sub>GS</sub> ≥ 10V I <sub>D</sub> = 150A	-	5.0	V
STATIC DRAIN-SOURCE ON-STATE RESISTANCE	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V I <sub>D</sub> = 75A	-	.035	OHM
ZERO GATE VOLTAGE DRAIN CURRENT	I <sub>DSS</sub>	V <sub>GS</sub> = 0V V <sub>DS</sub> = 400V	-	1.5	mA

(1) T<sub>J</sub> = 25°C TO 150°C.

(2) PULSE TEST: PULSE WIDTH < 300μS, DUTY CYCLE < 2%.

(3) TESTS ARE PERFORMED AT ELEMENT EVALUATION. TEST CONDITIONS AND LIMITS APPLY TO EACH MOSFET SEPARATELY.